

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

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# 2SK1623(L), 2SK1623(S)

Silicon N-Channel MOS FET

**RENESAS**

ADE-208-1299 (Z)  
1st. Edition  
Mar. 2001

## Application

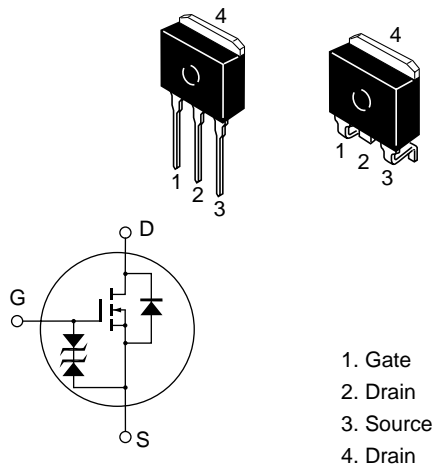
High speed power switching

## Features

- Low on-resistance
- High speed switching
- 4 V gate drive device
  - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

## Outline

LDBPAK



## 2SK1623(L), 2SK1623(S)

### Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{(BR)DSS}$	100	V
Gate to source voltage	$V_{GSS}$	±20	V
Drain current	$I_D$	20	A
Drain peak current	$I_{D(pulse)}^{*1}$	80	A
Body to drain diode reverse drain current	$I_{DR}$	20	A
Channel dissipation	$P_{ch}^{*2}$	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. PW 10 μs, duty cycle 1%

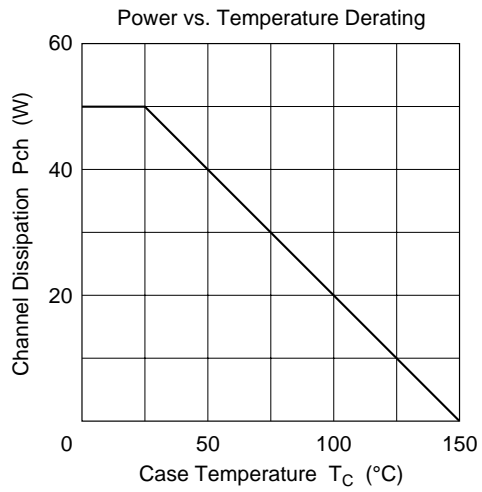
2. Value at T<sub>c</sub> = 25°C

## Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	—	—	V	$I_D = 10 \text{ mA}$ , $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	$\pm 20$	—	—	V	$I_G = \pm 100 \text{ }\mu\text{A}$ , $V_{DS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	$\pm 10$	$\mu\text{A}$	$V_{GS} = \pm 16 \text{ V}$ , $V_{DS} = 0$
Zero gate voltage drain current	$I_{DSS}$	—	—	250	$\mu\text{A}$	$V_{DS} = 80 \text{ V}$ , $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	—	2.0	V	$I_D = 1 \text{ mA}$ , $V_{DS} = 10 \text{ V}$
Static Drain to source on state resistance	$R_{DS(on)}$	—	0.065	0.085		$I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}^{*1}$
		—	0.085	0.12		$I_D = 10 \text{ A}$ , $V_{GS} = 4 \text{ V}^{*1}$
Forward transfer admittance	$ y_{fs} $	10	16	—	S	$I_D = 10 \text{ A}$ , $V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	$C_{iss}$	—	1300	—	pF	$V_{DS} = 10 \text{ V}$ , $V_{GS} = 0$ ,
Output capacitance	$C_{oss}$	—	540	—	pF	$f = 1 \text{ MHz}$
Reverse transfer capacitance	$C_{rss}$	—	160	—	pF	
Turn-on delay time	$t_{d(on)}$	—	12	—	ns	$I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$ ,
Rise time	$t_r$	—	100	—	ns	$R_L = 3$
Turn-off delay time	$t_{d(off)}$	—	300	—	ns	
Fall time	$t_f$	—	150	—	ns	
Body to drain diode forward voltage	$V_{DF}$	—	1.3	—	V	$I_F = 20 \text{ A}$ , $V_{GS} = 0$
Body to drain diode reverse recovery time	$t_{rr}$	—	300	—	ns	$I_F = 20 \text{ A}$ , $V_{GS} = 0$ , $di_F/dt = 50 \text{ A}/\mu\text{s}$

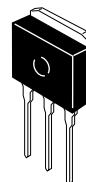
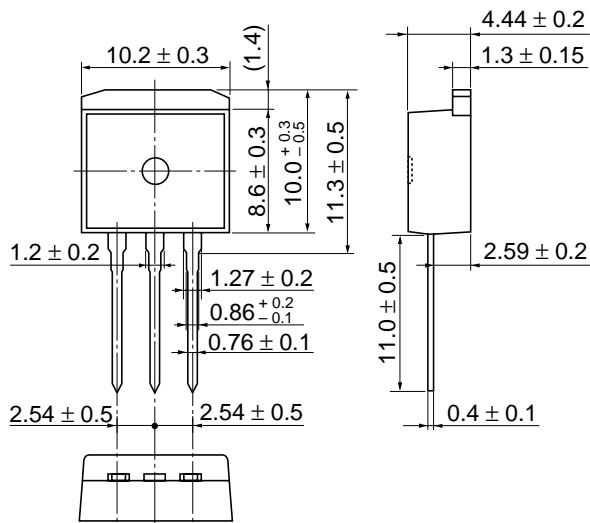
Note 1. Pulse test

See characteristic curves of 2SK1302.



Package Dimensions

As of January, 2001  
Unit: mm

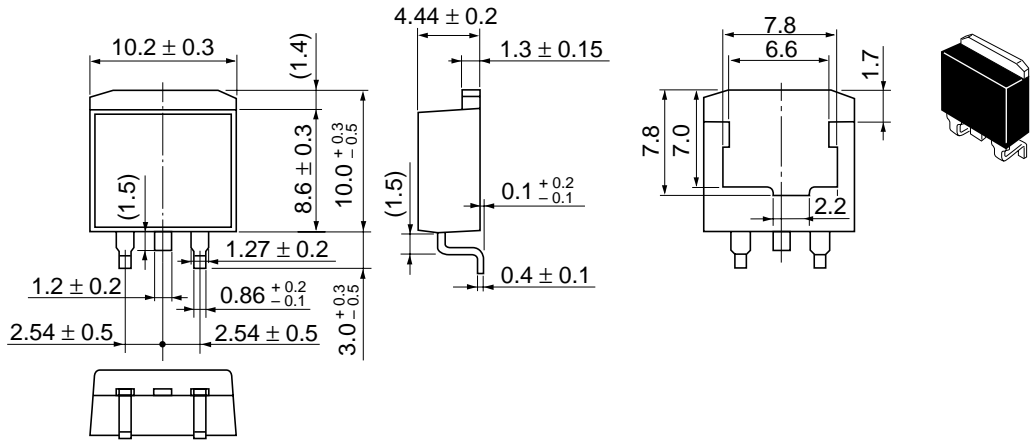


Hitachi Code	LDBPAK (L)
JEDEC	—
EIAJ	—
Mass (reference value)	1.4 g

# 2SK1623(L), 2SK1623(S)

As of January, 2001

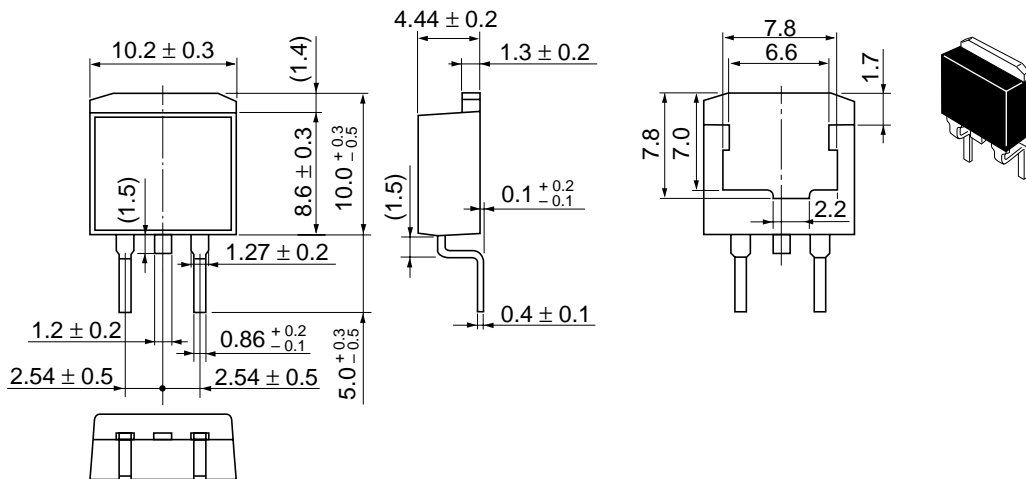
Unit: mm



Hitachi Code	LDBAK (S)-(1)
JEDEC	—
EIAJ	—
Mass (reference value)	1.3 g

As of January, 2001

Unit: mm



Hitachi Code	LDPAK (S)-(2)
JEDEC	—
EIAJ	—
Mass (reference value)	1.35 g

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